This Sheet Has Been Replaced



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ABSTRACT OF THE DISCLOSURE

A wiring board for bump bonding which allows to prevent the occurrence of broken connections between bumps and wiring, and has small deviations in bump heights, and is superior in productivity; a semiconductor device assembled from the wiring board; and a manufacturing method of the wiring board for bump bonding are to be provided.

In manufacturing a wiring board for bump bonding using an insulating layer having a conductive layer provided on its one surface, first, on the one surface of the conductive layer, a first resist layer is provided, exposed and developed, and the first resist layer in an area other than bump formation sections is eliminated, the conductive layer is half-etched to form bumps, then after eliminating the first resist layer as necessary, a second resist layer is provided, exposed and developed, and by etching the exposed conductive layer, a wiring pattern is formed. Thereafter, after the resist on the wiring pattern is eliminated as necessary, a protective resist layer is provided on the entire surface of the wiring pattern side, exposed and developed, and the surfaces of the bumps are exposed, then the protective resist layer is cured. Via holes are then formed by etching from the surface of the insulating layer side in desired sections, and the exposed bottom surfaces of the via holes and the surfaces of the bumps are metal-plated.

Figure 1